

MC10H162

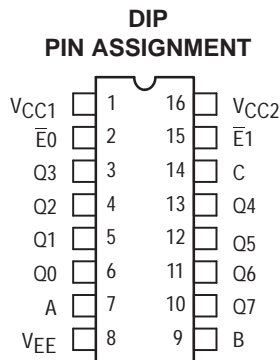
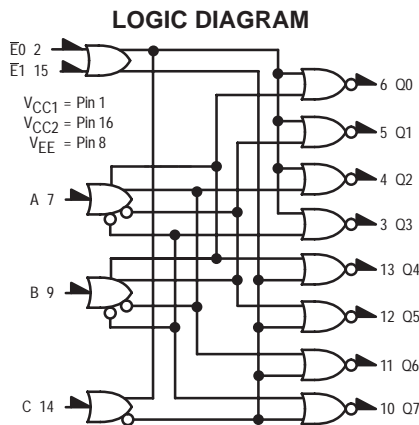
Binary to 1-8 Decoder (High)

The MC10H162 provides parallel decoding of a three bit binary word to one of eight lines. The MC10H162 is useful in high-speed multiplexer/ demultiplexer applications.

The MC10H162 is designed to decode a three bit input word to one of eight output lines. The MC10H162 output will be high when selected while all other output are low. The enable inputs, when either or both are high, force all outputs low.

The MC10H162 is a true parallel decoder. This eliminates unequal parallel path delay times found in other decoder designs. These devices are ideally suited for multiplexer/demultiplexer applications.

- Propagation Delay, 1.0 ns Typical
- Power Dissipation, 315 mW Typical (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible



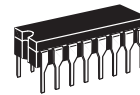
Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



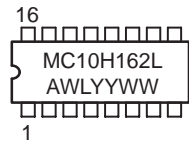
ON Semiconductor

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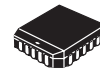
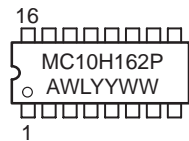
MARKING DIAGRAMS



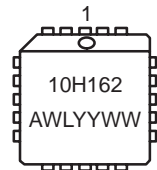
**CDIP-16
L SUFFIX
CASE 620**



**PDIP-16
P SUFFIX
CASE 648**



**PLCC-20
FN SUFFIX
CASE 775**



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

TRUTH TABLE

INPUTS					OUTPUTS							
E0	E1	C	B	A	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
L	L	L	L	L	H	L	L	L	L	L	L	L
L	L	L	L	H	L	L	H	L	L	L	L	L
L	L	L	H	H	L	L	L	L	H	L	L	L
L	L	L	H	L	L	L	L	L	L	H	L	L
L	L	H	H	H	L	L	L	L	L	L	H	L
L	L	H	H	L	L	L	L	L	L	L	L	H
L	L	H	L	H	L	L	L	L	L	L	L	L
L	L	H	L	L	L	L	L	L	L	L	L	L
H	X	X	X	X	L	L	L	L	L	L	L	L
X	H	X	X	X	L	L	L	L	L	L	L	L

ORDERING INFORMATION

Device	Package	Shipping
MC10H162L	CDIP-16	25 Units/Rail
MC10H162P	PDIP-16	25 Units/Rail
MC10H162FN	PLCC-20	46 Units/Rail

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MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply ($V_{CC} = 0$)	-8.0 to 0	Vdc
V_I	Input Voltage ($V_{CC} = 0$)	0 to V_{EE}	Vdc
I_{out}	Output Current – Continuous – Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range – Plastic – Ceramic	-55 to +150 -55 to +165	°C °C

ELECTRICAL CHARACTERISTICS ($V_{EE} = -5.2\text{ V} \pm 5\%$) (See Note 1.)

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
I_E	Power Supply Current	–	84	–	76	–	84	mA
I_{inH}	Input Current High	–	465	–	275	–	275	μA
I_{inL}	Input Current Low	0.5	–	0.5	–	0.3	–	μA
V_{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V_{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V_{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V_{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

AC PARAMETERS

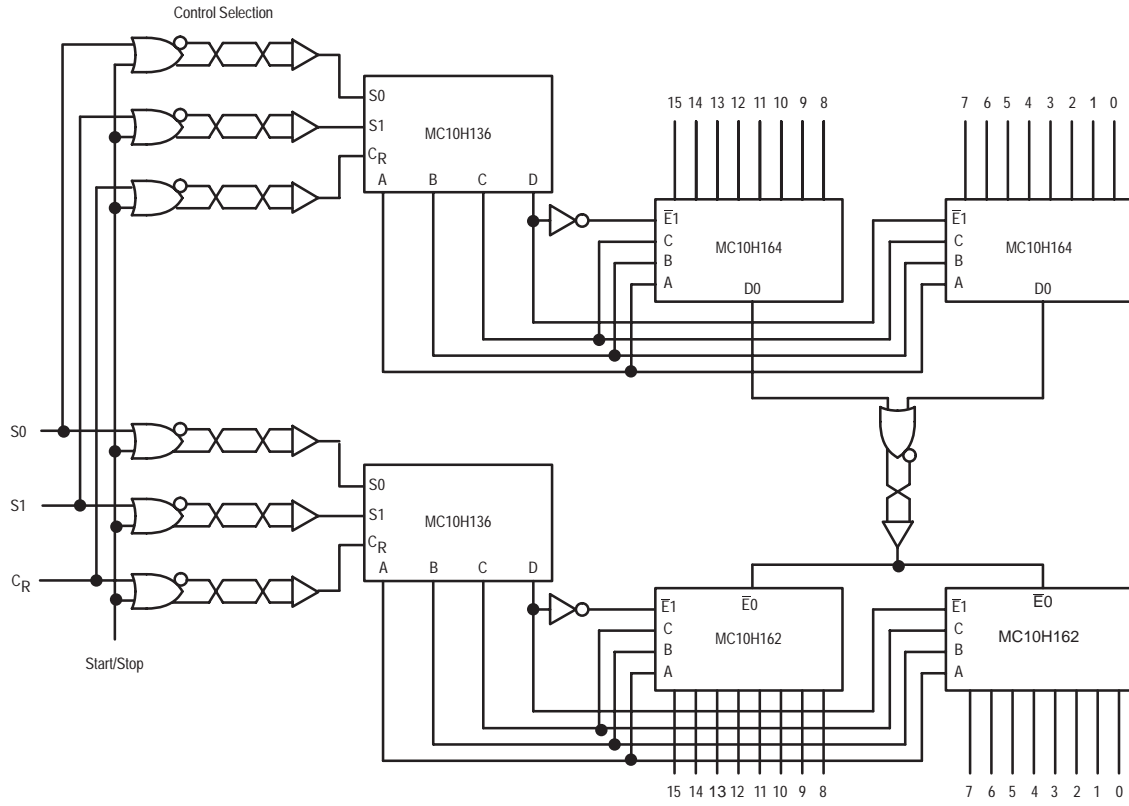
Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
t_{pd}	Propagation Delay Pins 7, 9, 14 Only Pins 2, 15 Only	0.7	2.0	0.7	2.1	0.8	2.5	ns
		0.8	2.3	0.8	2.4	0.9	2.6	
t_r	Rise Time	0.6	1.8	0.6	1.9	0.6	2.0	ns
t_f	Fall Time	0.6	1.8	0.6	1.9	0.6	2.0	ns

1. Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts.

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TYPICAL APPLICATIONS

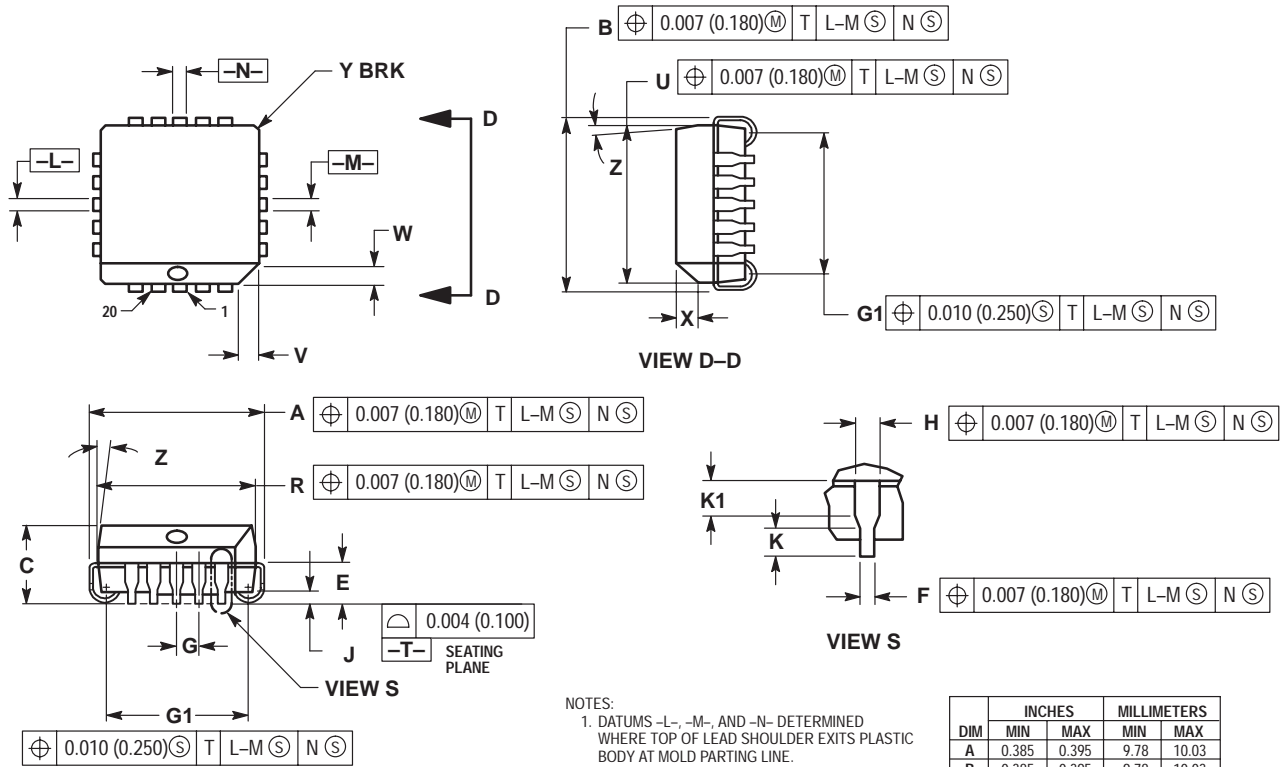
FIGURE 1 – HIGH SPEED 16-BIT MULTIPLEXER/DEMULTIPLEXER



MC10H162

PACKAGE DIMENSIONS

PLCC-20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775-02
ISSUE C



NOTES:

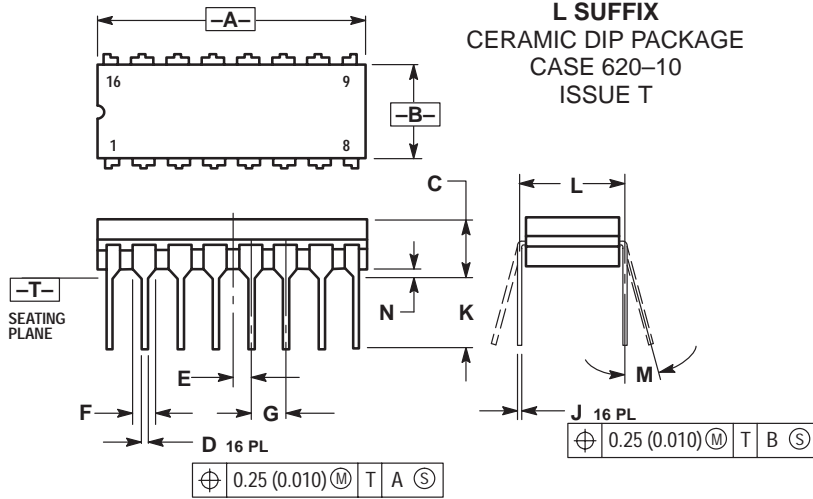
- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

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PACKAGE DIMENSIONS

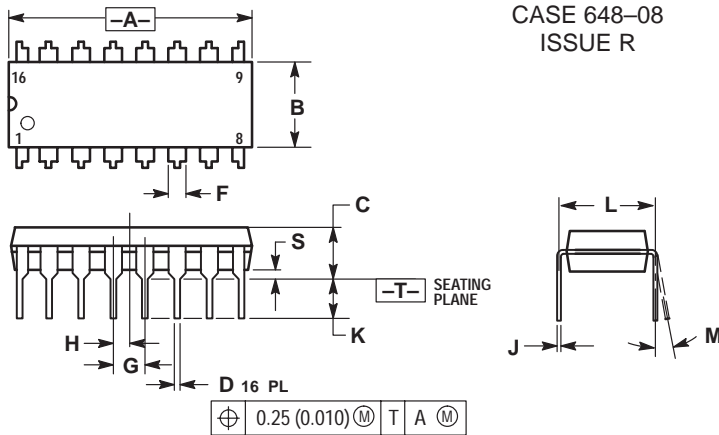
CDIP-16 L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE T



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

PDIP-16 P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R




- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

Notes

Notes

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